# CEPC Silicon Tracker Progress Report (17)

Qi Yan *on behalf of the Silicon Tracker Group*Jan 6, 2025, IHEP

## **Progress on Silicon Tracker Ref-TDR**

The Silicon Tracker group is dedicated to finalizing the drafting of the Silicon Tracker chapter of the Ref-TDR as soon as possible:

~90% of the content has been completed, with the full chapter nearing 100 pages.

The following topics will continue to be added:

- Overview of ITK and OTK
- Mechanical and thermal analysis of the endcap
- Our group has undergone two rounds of weekly global internal reading, discussion, and revision of the Silicon Tracker Ref-TDR. We will continue this paper reading until the chapter reaches certain quality level.
- I am full-time working on drafting and systematically revising of the entire chapter of the Silicon Tracker Ref-TDR during the last few months.

### Main Contributors and Sections of Silicon Tracker Ref-TRD

(Blue indicated the parts after my pre-revision)

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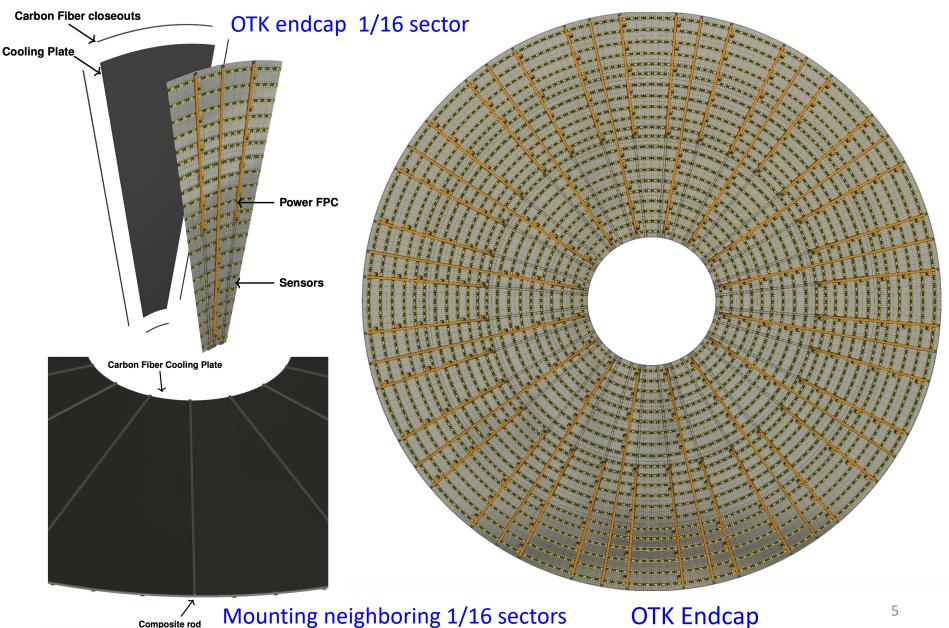
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#### **Ref-TDR Continuously Incorporates Latest Elaborate Design**



Composite rod

#### Weekly Highlight Invited Talk in Silicon Tracker Group

- We hold weekly invited highlight talk within the Silicon Tracker group, covering topics such as the progress on detector developments, electronics, mechanics (cooling), and software, with all staff and students in the group involved to present. The focus is on sharing, communication, and encouragement, and the content can include current work, future plan, or work outside of CEPC.
- Good work will be selected for CEPC Day to have sufficient recognition.
   Exceptional work will also be recommended to represent the group at conference presentations.

# 高精度时间时间测量

严雄波

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